

Material Declaration Report



Package Type:	SC70-4
Pericom Package Code:	C04 (Pb-free)
RoHS Compliance:	Yes
Applicable Exemption:	N/A

Component Weight (mg):	6.258
Termination Plating:	Matte Tin
JESD 97 Pb-free Category:	e3
Plating Thickness (um):	7-17
Tin Whisker Mitigation:	Anneal, 150C/1.5hr

MSL Rating:	1
Peak Body Temp (C):	260
Max Time (sec):	10
Reflow Cycles:	3
Rev Date:	Mar.05.2009

Homogeneous Material Declaration

MATERIAL ITEM	MATERIAL WEIGHT(mg)	ASSEMBLY SUBCON	MATERIAL COMPOSITION	CAS NO.	COMPOSITION %	COMPOSITION WEIGHT(mg)
MOLD COMPOUND	3.656	CJE	Silica, vitreous	60676-86-0	80.00	2.92480
			Silicon dioxide	7631-86-9	17.00	0.62152
			Boron zinc hydroxide oxide (B12Zn4(OH)14O15)	138265-88-0	1.00	0.03656
			Phenol-formaldehyde polymer	9003-35-4	1.00	0.03656
			Carbon black	1333-86-4	1.00	0.03656
LEAD FRAME	1.623		Nickel	7440-02-0	41.00	0.66543
			Manganese	7439-96-5	0.80	0.01298
			Cobalt	7440-48-4	0.50	0.00812
			Silicon	7440-21-3	0.30	0.00487
			Phosphorus	7723-14-0	0.025	0.00041
			Sulfur	7704-34-9	0.025	0.00041
			Carbon	7440-44-0	0.050	0.00081
			Iron	7439-89-6	57.290	0.92982
			Silver	7440-22-4	0.010	0.00016
			TERMINATION PLATING	0.2270		Tin
Impurity	Proprietary	0.10				0.00023
SILICON DIE	0.350		Silicon	7440-21-3	99.763	0.34917
			Aluminum(Al)	7429-90-5	0.200	0.00070
			Copper(Cu)	7440-50-8	0.001	0.00000
			Titanium(Ti)	7440-32-6	0.028	0.00010
			Phosphorus(P)	7664-38-2	0.003	0.00001
			Boron(B)	7440-42-8	0.005	0.00002
DIE ATTACH EPOXY	0.353		Silica, crystalline	14808-60-7	42.50	0.15003
			Epoxy resin1	Secret	25.00	0.08825
			Epoxy resin2	Secret	15.00	0.05295
			Epoxy resin modifier	Secret	15.00	0.05295
			Amine	Secret	2.50	0.00883
GOLD WIRE	0.049		Au	7440-57-5	99.99	0.04900
			Other materials	Secret	0.01	0.00000

NOTE: The device contents disclosed are approximated and are based on engineering estimates.

3rd Party Analysis Results (PPM)

MATERIAL	Pb	Hg	Cr+6	Cd	PBB	PBDE
Mold Compound	<2	<2	<2	<2	<5	<5
Leadframe	<50	<2	<2	<2	<5	<5
Device Silicon Die	<2	<2	<2	<2	<5	<5
Die Attach Epoxy	<2	<2	<2	<2	<5	<5
Gold Wire	<2	<2	<2	<2	<5	<5
Solder Plating	<2	<2	<2	<2	<5	<5

ROHS MATERIAL COMPOSITION DECLARATION

EU RoHS Directive 2002/95/EC and China RoHS Directive SJ/T11363-2006	Declaration Statement:	Quantity limit of 0.1% (1000 PPM) by mass in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium(Cr+6), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE); and Quantity limit of 0.01% (100 PPM) for Cadmium					
		Pb	Hg	Cr+6	Cd	PBB	PBDE
	<1000ppm	<1000ppm	<1000ppm	<100ppm	<1000ppm	<1000ppm	
	O	O	O	O	O	O	

O: Indicates that this toxic or hazardous substance contained in all of the homogeneous materials for this part is below the limit requirement in SJ/T11363-2006.
X: Indicates that this toxic or hazardous substance contained in at least one of the homogeneous materials used for this part is above the limit requirement in SJ/T11363-2006.